Chip Scale Review®

ChipScaleReview.com — *The Future of Semiconductor Packaging*

2017 Editorial Calendar

(Editorial close date: 4/21)	**July • August**	* indicates show distribution
OSATs: Challenges for revenue growth High-density advanced packaging solutions for today's OSATs & foundries		• **ICEPT 2017** Harbin, China (Aug 16-19) • **BiTS China 2017** Shanghai, China (Sept 7) • **SEMICON Taiwan** * Taipei, Taiwan (Sept 13-15) • **SMTA International** * Rosemont, IL (Sept 17-21) • **European MEMS & Sensors Summit** Grenoble, France (Sept 20-22)
Wafer thinning		
TSV technologies for next-gen application challenges		
Die attach solutions		
Performance and cost for 2.5D packaging		
3D metrology challenges		
3D capacitors for on-chip integration		
HVM of chip-on-submount		

Ad Space Close Jun 30 - Ad Materials Close Jul 7

(Editorial close date: 6/9)	**September • October**	* indicates show distribution
Technology trends in photonics packaging		• **IMAPS 2017** * Raleigh, NC (Oct 9-12) • **IWLPC-International Wafer-Level Packaging Conference & Exhibition** * San Jose, CA (Oct 24-26) • **International Test Conference (ITC)** Fort Worth, TX (Oct 31- Nov 2) • **MEMS & Sensors Executive Congress** Napa Valley, CA (Nov 1-2) • **SEMICON Europa** Munich, Germany (Nov 14-17)
Lithographic challenges for PLP		
Packaging ICs/sensors for automotive applications		
High-volume via formation in solid-core glass for IC substrates		
Excimer laser ablation for fine RDL routings		
Final test		
Packaging SiPs/SiP supply chain		
Interferometry sensors for metrology applications		
Non-destructive 3D X-ray imaging for advanced packaging failure analysis		

Ad Space Close Sep 9 - Ad Materials Close Sep 16

(Editorial close date: 9/1)	**November • December**	* indicates show distribution
2.5D & 3D ICs		• **3D ASIP Conference** * Burlingame, CA (Dec 5-7) • **EPTC 2017** Singapore (Dec 6-9) • **SEMICON Japan** Tokyo, Japan (Dec 13-15) • **SEMI European 3D Summit** * Grenoble, France (Jan 22-24, 2018)
Probe technology for advanced 3D chips		
China IC market update		
Packaging challenges for automotive applications		
Optimization of fan-out die placement		
What's now & next in MEMS & Sensors		
TCB – Part 2		
IC cleaning process		
Flip-chip assembly reliability		

International directory of bonding equipment for 2.5D & 3D assembly

Ad Space Close Nov 4 - Materials Close Nov 11

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Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

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